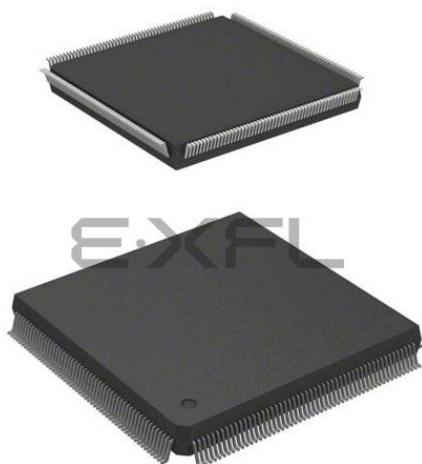




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	276480
Number of I/O	147
Number of Gates	1500000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/m1a3pe1500-1pqg208i

Temperature Grade Offerings

Package	A3PE600	A3PE1500	A3PE3000
Cortex-M1 Devices		M1A3PE1500	M1A3PE3000
PQ208	C, I	C, I	C, I
FG256	C, I	–	–
FG324	–	–	C, I
FG484	C, I	C, I	C, I
FG676	–	C, I	–
FG896	–	–	C, I

Note: C = Commercial temperature range: 0°C to 70°C ambient temperature
 I = Industrial temperature range: –40°C to 85°C ambient temperature

Speed Grade and Temperature Grade Matrix

Temperature Grade	Std.	–1	–2
C ¹	✓	✓	✓
I ²	✓	✓	✓

Notes:

1. C = Commercial temperature range: 0°C to 70°C ambient temperature
2. I = Industrial temperature range: –40°C to 85°C ambient temperature

References made to ProASIC3E devices also apply to ARM-enabled ProASIC3E devices. The ARM-enabled part numbers start with M1 (Cortex-M1).

Contact your local Microsemi SoC Products Group representative for device availability:
www.microsemi.com/index.php?option=com_content&id=135&lang=en&view=article.

Specify I/O States During Programming

Load from file... Save to file... ☐ Show BSR Details

	Port Name	Macro Cell	Pin Number	I/O State (Output Only)
	BIST	ADLIB:INBUF	T2	1
	BYPASS_IO	ADLIB:INBUF	K1	1
	CLK	ADLIB:INBUF	B1	1
	ENOUT	ADLIB:INBUF	J16	1
	LED	ADLIB:OUTBUF	M3	0
	MONITOR[0]	ADLIB:OUTBUF	B5	0
	MONITOR[1]	ADLIB:OUTBUF	C7	Z
	MONITOR[2]	ADLIB:OUTBUF	D9	Z
	MONITOR[3]	ADLIB:OUTBUF	D7	Z
	MONITOR[4]	ADLIB:OUTBUF	A11	Z
	OEa	ADLIB:INBUF	E4	Z
	OEb	ADLIB:INBUF	F1	Z
	OSC_EN	ADLIB:INBUF	K3	Z
	PAD[10]	ADLIB:BIBUF_LVCMOS33U	M8	Z
	PAD[11]	ADLIB:BIBUF_LVCMOS33D	R7	Z
	PAD[12]	ADLIB:BIBUF_LVCMOS33U	D11	Z
	PAD[13]	ADLIB:BIBUF_LVCMOS33D	C12	Z
	PAD[14]	ADLIB:BIBUF_LVCMOS33U	R6	Z

Help OK Cancel

Figure 1-3 • I/O States During Programming Window

- Click OK to return to the FlashPoint – Programming File Generator window.
I/O States during programming are saved to the ADB and resulting programming files after completing programming file generation.

Guidelines

Toggle Rate Definition

A toggle rate defines the frequency of a net or logic element relative to a clock. It is a percentage. If the toggle rate of a net is 100%, this means that this net switches at half the clock frequency. Below are some examples:

- The average toggle rate of a shift register is 100% as all flip-flop outputs toggle at half of the clock frequency.
- The average toggle rate of an 8-bit counter is 25%:
 - Bit 0 (LSB) = 100%
 - Bit 1 = 50%
 - Bit 2 = 25%
 - ...
 - Bit 7 (MSB) = 0.78125%
 - Average toggle rate = $(100\% + 50\% + 25\% + 12.5\% + \dots + 0.78125\%) / 8$

Enable Rate Definition

Output enable rate is the average percentage of time during which tristate outputs are enabled. When nontristate output buffers are used, the enable rate should be 100%.

Table 2-11 • Toggle Rate Guidelines Recommended for Power Calculation

Component	Definition	Guideline
α_1	Toggle rate of VersaTile outputs	10%
α_2	I/O buffer toggle rate	10%

Table 2-12 • Enable Rate Guidelines Recommended for Power Calculation

Component	Definition	Guideline
β_1	I/O output buffer enable rate	100%
β_2	RAM enable rate for read operations	12.5%
β_3	RAM enable rate for write operations	12.5%

Timing Characteristics

Table 2-31 • 3.3 V LVCMOS Wide Range High Slew

Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 2.7\text{ V}$

Drive Strength	Equivalent Software Default Drive Strength Option ¹	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
100 μA	4 mA	Std.	0.66	12.19	0.04	1.83	2.38	0.43	12.19	10.17	4.16	4.00	15.58	13.57	ns
		–1	0.56	10.37	0.04	1.55	2.02	0.36	10.37	8.66	3.54	3.41	13.26	11.54	ns
		–2	0.49	9.10	0.03	1.36	1.78	0.32	9.10	7.60	3.11	2.99	11.64	10.13	ns
100 μA	8 mA	Std.	0.66	7.85	0.04	1.83	2.38	0.43	7.85	6.29	4.71	4.97	11.24	9.68	ns
		–1	0.56	6.68	0.04	1.55	2.02	0.36	6.68	5.35	4.01	4.22	9.57	8.24	ns
		–2	0.49	5.86	0.03	1.36	1.78	0.32	5.86	4.70	3.52	3.71	8.40	7.23	ns
100 μA	12 mA	Std.	0.66	5.67	0.04	1.83	2.38	0.43	5.67	4.36	5.06	5.59	9.07	7.75	ns
		–1	0.56	4.82	0.04	1.55	2.02	0.36	4.82	3.71	4.31	4.75	7.71	6.59	ns
		–2	0.49	4.24	0.03	1.36	1.78	0.32	4.24	3.25	3.78	4.17	6.77	5.79	ns
100 μA	16 mA	Std.	0.66	5.35	0.04	1.83	2.38	0.43	5.35	3.96	5.15	5.76	8.75	7.35	ns
		–1	0.56	4.55	0.04	1.55	2.02	0.36	4.55	3.36	4.38	4.90	7.44	6.25	ns
		–2	0.49	4.00	0.03	1.36	1.78	0.32	4.00	2.95	3.85	4.30	6.53	5.49	ns
100 μA	24 mA	Std.	0.66	4.96	0.04	1.83	2.38	0.43	4.96	3.27	5.23	6.38	8.35	6.67	ns
		–1	0.56	4.22	0.04	1.55	2.02	0.36	4.22	2.78	4.45	5.43	7.11	5.67	ns
		–2	0.49	3.70	0.03	1.36	1.78	0.32	3.70	2.44	3.91	4.76	6.24	4.98	ns

Notes:

1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is $\pm 100\text{ }\mu\text{A}$. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
2. Software default selection highlighted in gray.
3. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-5](#) for derating values.

Table 2-40 • 1.8 V LVCMOS Low Slew
Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.7\text{ V}$

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.66	15.84	0.04	1.45	1.91	0.43	15.65	15.84	2.78	1.58	17.89	18.07	ns
	–1	0.56	13.47	0.04	1.23	1.62	0.36	13.31	13.47	2.37	1.35	15.22	15.37	ns
	–2	0.49	11.83	0.03	1.08	1.42	0.32	11.69	11.83	2.08	1.18	13.36	13.50	ns
4 mA	Std.	0.66	11.39	0.04	1.45	1.91	0.43	11.60	10.76	3.26	2.77	13.84	12.99	ns
	–1	0.56	9.69	0.04	1.23	1.62	0.36	9.87	9.15	2.77	2.36	11.77	11.05	ns
	–2	0.49	8.51	0.03	1.08	1.42	0.32	8.66	8.03	2.43	2.07	10.33	9.70	ns
6 mA	Std.	0.66	8.97	0.04	1.45	1.91	0.43	9.14	8.10	3.57	3.36	11.37	10.33	ns
	–1	0.56	7.63	0.04	1.23	1.62	0.36	7.77	6.89	3.04	2.86	9.67	8.79	ns
	–2	0.49	6.70	0.03	1.08	1.42	0.32	6.82	6.05	2.66	2.51	8.49	7.72	ns
8 mA	Std.	0.66	8.35	0.04	1.45	1.91	0.43	8.50	7.59	3.64	3.52	10.74	9.82	ns
	–1	0.56	7.10	0.04	1.23	1.62	0.36	7.23	6.45	3.10	3.00	9.14	8.35	ns
	–2	0.49	6.24	0.03	1.08	1.42	0.32	6.35	5.66	2.72	2.63	8.02	7.33	ns
12 mA	Std.	0.66	7.94	0.04	1.45	1.91	0.43	8.09	7.56	3.74	4.11	10.32	9.80	ns
	–1	0.56	6.75	0.04	1.23	1.62	0.36	6.88	6.43	3.18	3.49	8.78	8.33	ns
	–2	0.49	5.93	0.03	1.08	1.42	0.32	6.04	5.65	2.79	3.07	7.71	7.32	ns
16 mA	Std.	0.66	7.94	0.04	1.45	1.91	0.43	8.09	7.56	3.74	4.11	10.32	9.80	ns
	–1	0.56	6.75	0.04	1.23	1.62	0.36	6.88	6.43	3.18	3.49	8.78	8.33	ns
	–2	0.49	5.93	0.03	1.08	1.42	0.32	6.04	5.65	2.79	3.07	7.71	7.32	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-5](#) for derating values.

3.3 V PCI, 3.3 V PCI-X

Peripheral Component Interface for 3.3 V standard specifies support for 33 MHz and 66 MHz PCI Bus applications.

Table 2-45 • Minimum and Maximum DC Input and Output Levels

3.3 V PCI/PCI-X	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IIL ¹	IIH ²
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ³	Max. mA ³	μA ⁴	μA ⁴
Per PCI specification	Per PCI curves										10	10

Notes:

1. IIL is the input leakage current per I/O pin over recommended operation conditions where $-0.3\text{ V} < V_{IN} < V_{IL}$.
2. IIH is the input leakage current per I/O pin over recommended operating conditions $V_{IH} < V_{IN} < V_{CCI}$. Input current is larger when operating outside recommended ranges.
3. Currents are measured at high temperature (100°C junction temperature) and maximum voltage.
4. Currents are measured at 85°C junction temperature.

AC loadings are defined per the PCI/PCI-X specifications for the datapath; Microsemi loadings for enable path characterization are described in [Figure 2-11](#).

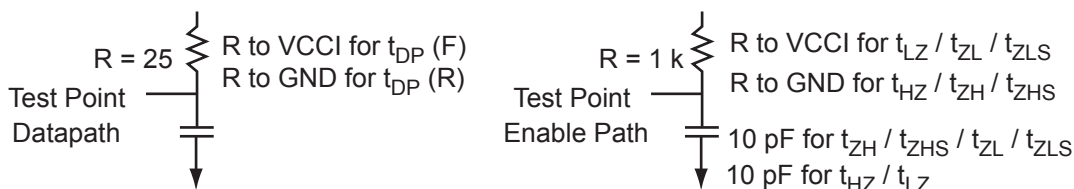


Figure 2-11 • AC Loading

AC loadings are defined per PCI/PCI-X specifications for the datapath; Microsemi loading for tristate is described in [Table 2-46](#).

Table 2-46 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ.) (V)	C _{LOAD} (pF)
0	3.3	0.285 * VCCI for t _{DP(R)} 0.615 * VCCI for t _{DP(F)}	—	10

Note: *Measuring point = Vtrip. See [Table 2-15 on page 2-18](#) for a complete table of trip points.

Timing Characteristics

Table 2-47 • 3.3 V PCI/PCI-X

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V

Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{ZHS}	Units
Std.	0.66	2.81	0.04	1.05	1.67	0.43	2.86	2.00	3.28	3.61	5.09	4.23	ns
–1	0.56	2.39	0.04	0.89	1.42	0.36	2.43	1.70	2.79	3.07	4.33	3.60	ns
–2	0.49	2.09	0.03	0.78	1.25	0.32	2.13	1.49	2.45	2.70	3.80	3.16	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-5](#) for derating values.

I/O Register Specifications

Fully Registered I/O Buffers with Synchronous Enable and Asynchronous Preset

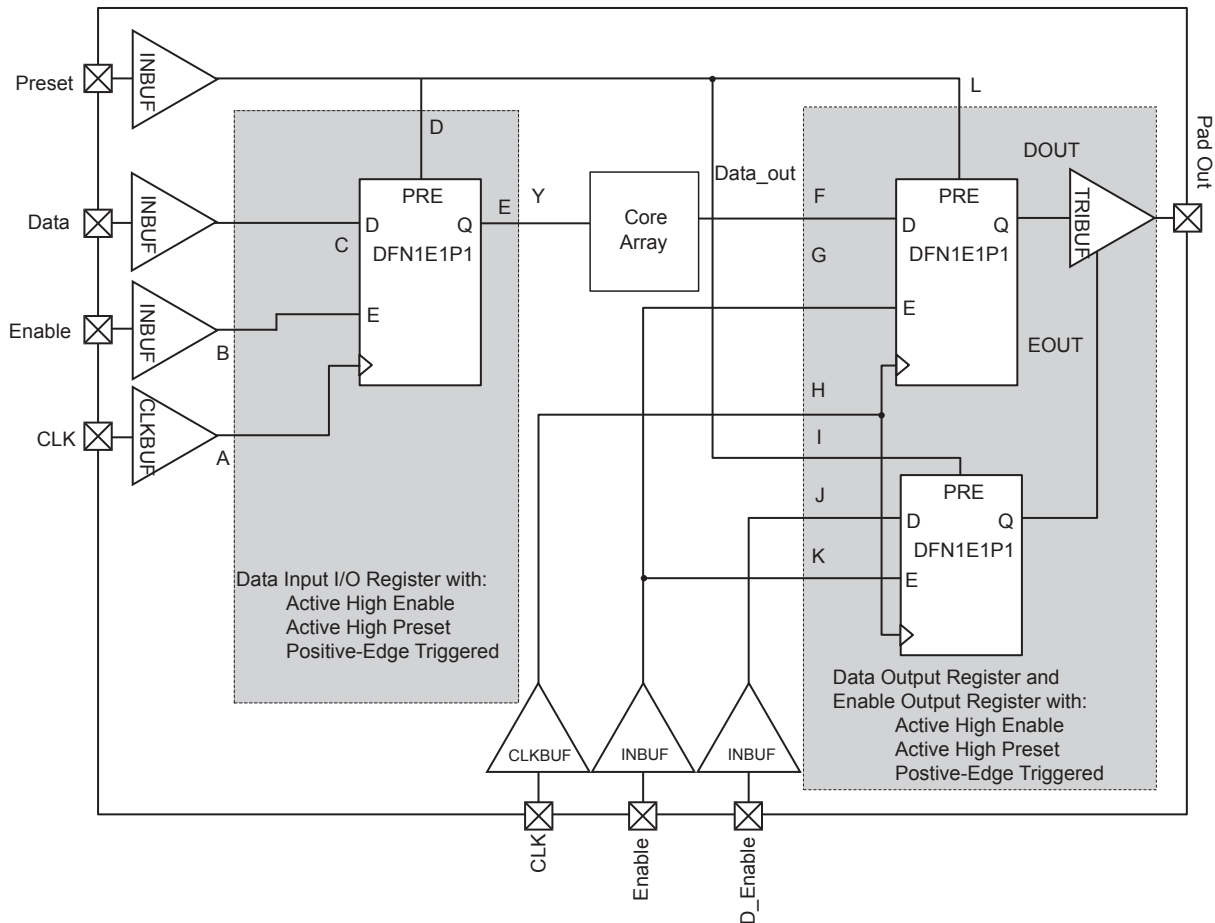


Figure 2-25 • Timing Model of Registered I/O Buffers with Synchronous Enable and Asynchronous Preset

Table 2-85 • Parameter Definition and Measuring Nodes

Parameter Name	Parameter Definition	Measuring Nodes (from, to)*
t_{OCLKQ}	Clock-to-Q of the Output Data Register	HH, DOUT
t_{OSUD}	Data Setup Time for the Output Data Register	FF, HH
t_{OHD}	Data Hold Time for the Output Data Register	FF, HH
t_{OSUE}	Enable Setup Time for the Output Data Register	GG, HH
t_{OHE}	Enable Hold Time for the Output Data Register	GG, HH
t_{OCLR2Q}	Asynchronous Clear-to-Q of the Output Data Register	LL, DOUT
$t_{OREMCLR}$	Asynchronous Clear Removal Time for the Output Data Register	LL, HH
$t_{ORECCLR}$	Asynchronous Clear Recovery Time for the Output Data Register	LL, HH
t_{OECLKQ}	Clock-to-Q of the Output Enable Register	HH, EOUT
t_{OESUD}	Data Setup Time for the Output Enable Register	JJ, HH
t_{OEHD}	Data Hold Time for the Output Enable Register	JJ, HH
t_{OESUE}	Enable Setup Time for the Output Enable Register	KK, HH
t_{OEHE}	Enable Hold Time for the Output Enable Register	KK, HH
$t_{OECLR2Q}$	Asynchronous Clear-to-Q of the Output Enable Register	II, EOUT
$t_{OEREMCLR}$	Asynchronous Clear Removal Time for the Output Enable Register	II, HH
$t_{OERECCLR}$	Asynchronous Clear Recovery Time for the Output Enable Register	II, HH
t_{ICLKQ}	Clock-to-Q of the Input Data Register	AA, EE
t_{ISUD}	Data Setup Time for the Input Data Register	CC, AA
t_{IHD}	Data Hold Time for the Input Data Register	CC, AA
t_{ISUE}	Enable Setup Time for the Input Data Register	BB, AA
t_{IHE}	Enable Hold Time for the Input Data Register	BB, AA
t_{ICLR2Q}	Asynchronous Clear-to-Q of the Input Data Register	DD, EE
$t_{IREMCLR}$	Asynchronous Clear Removal Time for the Input Data Register	DD, AA
$t_{IRECCLR}$	Asynchronous Clear Recovery Time for the Input Data Register	DD, AA

Note: *See Figure 2-26 on page 2-55 for more information.

Output DDR Module

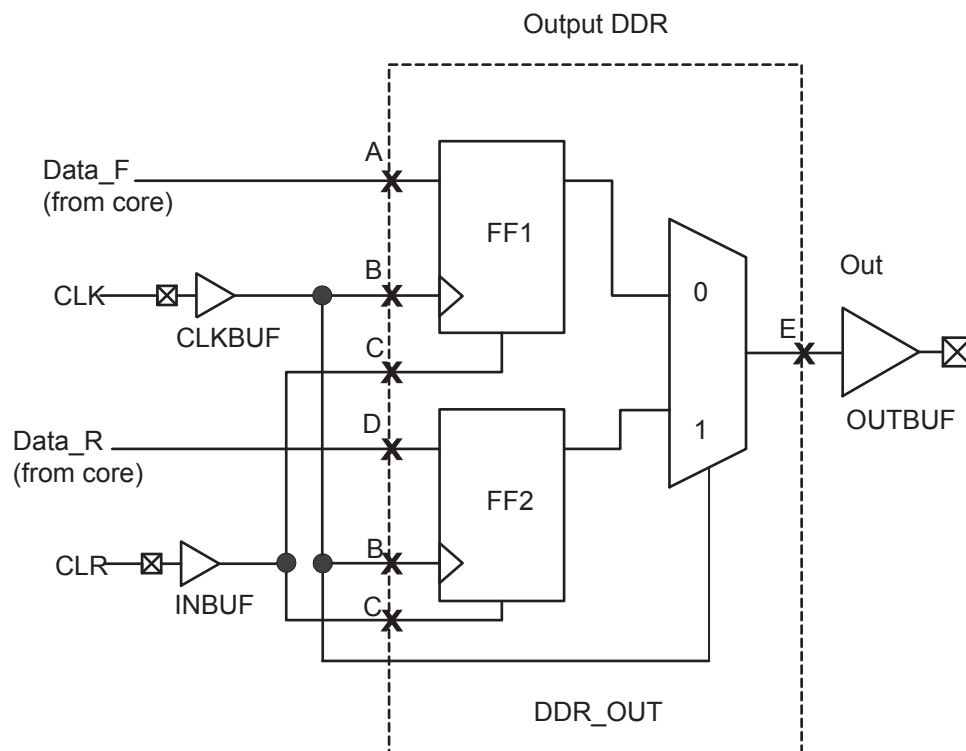


Figure 2-32 • Output DDR Timing Model

Table 2-91 • Parameter Definitions

Parameter Name	Parameter Definition	Measuring Nodes (from, to)
t_{DDROCLKQ}	Clock-to-Out	B, E
$t_{\text{DDROCLR2Q}}$	Asynchronous Clear-to-Out	C, E
$t_{\text{DDROREMCLR}}$	Clear Removal	C, B
$t_{\text{DDRORECCLR}}$	Clear Recovery	C, B
t_{DDROSUD1}	Data Setup Data_F	A, B
t_{DDROSUD2}	Data Setup Data_R	D, B
t_{DDROHD1}	Data Hold Data_F	A, B
t_{DDROHD2}	Data Hold Data_R	D, B

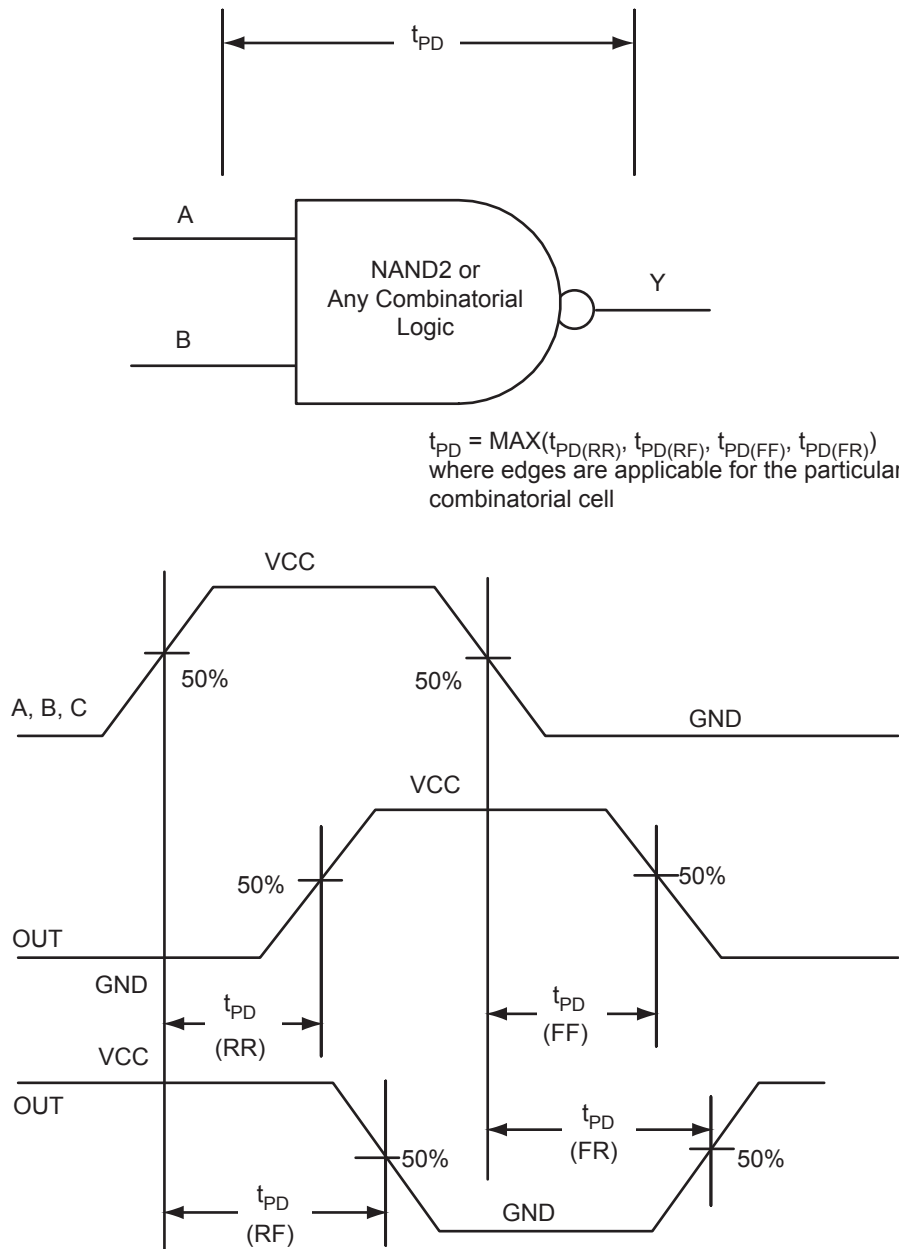


Figure 2-35 • Timing Model and Waveforms

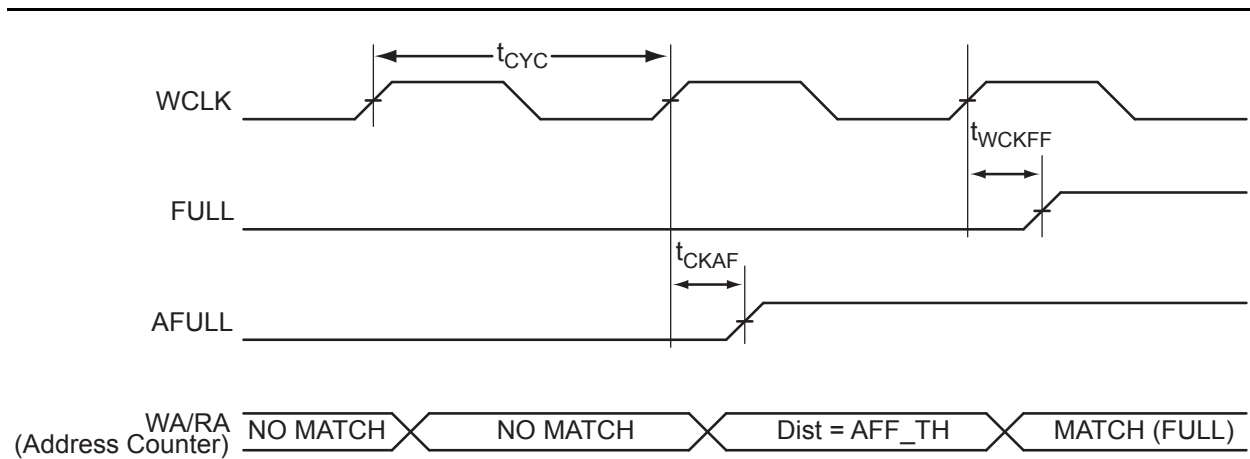


Figure 2-51 • FIFO FULL Flag and AFULL Flag Assertion

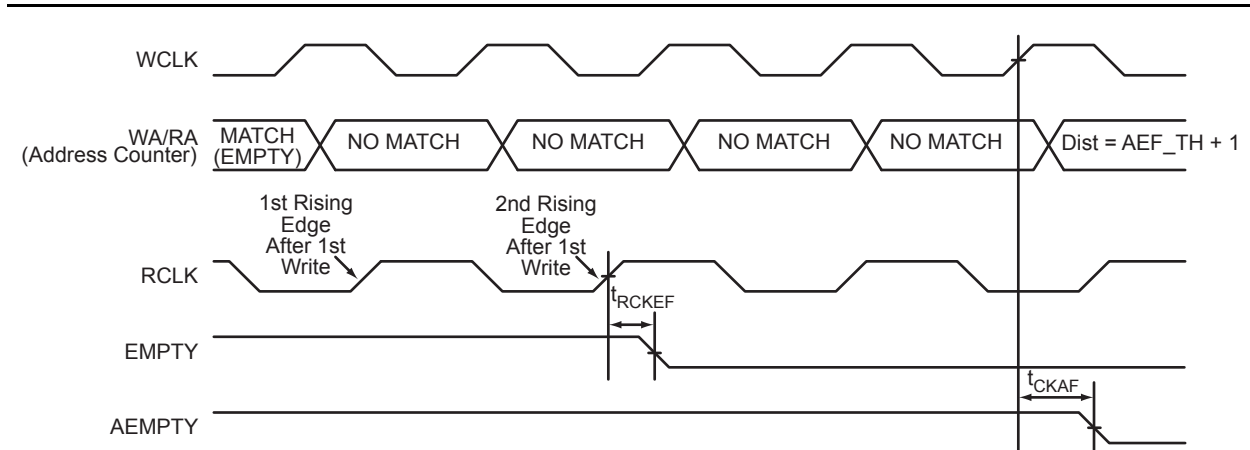


Figure 2-52 • FIFO EMPTY Flag and AEMPTY Flag Deassertion

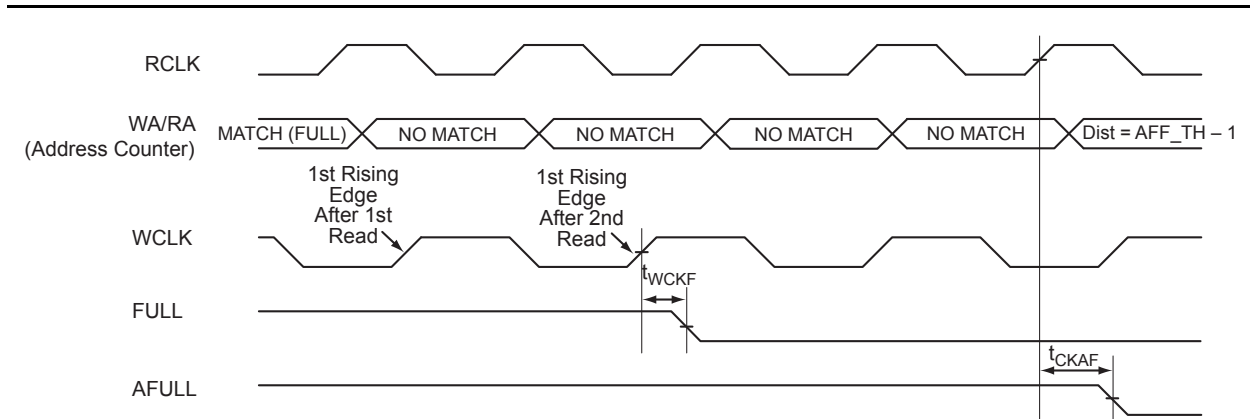


Figure 2-53 • FIFO FULL Flag and AFULL Flag Deassertion

VJTAG

JTAG Supply Voltage

Low power flash devices have a separate bank for the dedicated JTAG pins. The JTAG pins can be run at any voltage from 1.5 V to 3.3 V (nominal). Isolating the JTAG power supply in a separate I/O bank gives greater flexibility in supply selection and simplifies power supply and PCB design. If the JTAG interface is neither used nor planned for use, the VJTAG pin together with the TRST pin could be tied to GND. It should be noted that VCC is required to be powered for JTAG operation; VJTAG alone is insufficient. If a device is in a JTAG chain of interconnected boards, the board containing the device can be powered down, provided both VJTAG and VCC to the part remain powered; otherwise, JTAG signals will not be able to transition the device, even in bypass mode.

Microsemi recommends that VPUMP and VJTAG power supplies be kept separate with independent filtering capacitors rather than supplying them from a common rail.

VPUMP

Programming Supply Voltage

For programming, VPUMP should be 3.3 V nominal. During normal device operation, VPUMP can be left floating or can be tied (pulled up) to any voltage between 0 V and the VPUMP maximum. Programming power supply voltage (VPUMP) range is listed in the datasheet.

When the VPUMP pin is tied to ground, it will shut off the charge pump circuitry, resulting in no sources of oscillation from the charge pump circuitry.

For proper programming, 0.01 μ F and 0.33 μ F capacitors (both rated at 16 V) are to be connected in parallel across VPUMP and GND, and positioned as close to the FPGA pins as possible.

Microsemi recommends that VPUMP and VJTAG power supplies be kept separate with independent filtering capacitors rather than supplying them from a common rail.

User-Defined Supply Pins

VREF

I/O Voltage Reference

Reference voltage for I/O minibanks. VREF pins are configured by the user from regular I/Os, and any I/O in a bank, except JTAG I/Os, can be designated the voltage reference I/O. Only certain I/O standards require a voltage reference—HSTL (I) and (II), SSTL2 (I) and (II), SSTL3 (I) and (II), and GTL/GTL+. One VREF pin can support the number of I/Os available in its minibank.

User Pins

I/O

User Input/Output

The I/O pin functions as an input, output, tristate, or bidirectional buffer. Input and output signal levels are compatible with the I/O standard selected.

During programming, I/Os become tristated and weakly pulled up to VCCI. With VCCI, VMV, and VCC supplies continuously powered up, when the device transitions from programming to operating mode, the I/Os are instantly configured to the desired user configuration.

Unused I/Os are configured as follows:

- Output buffer is disabled (with tristate value of high impedance)
- Input buffer is disabled (with tristate value of high impedance)
- Weak pull-up is programmed

GL

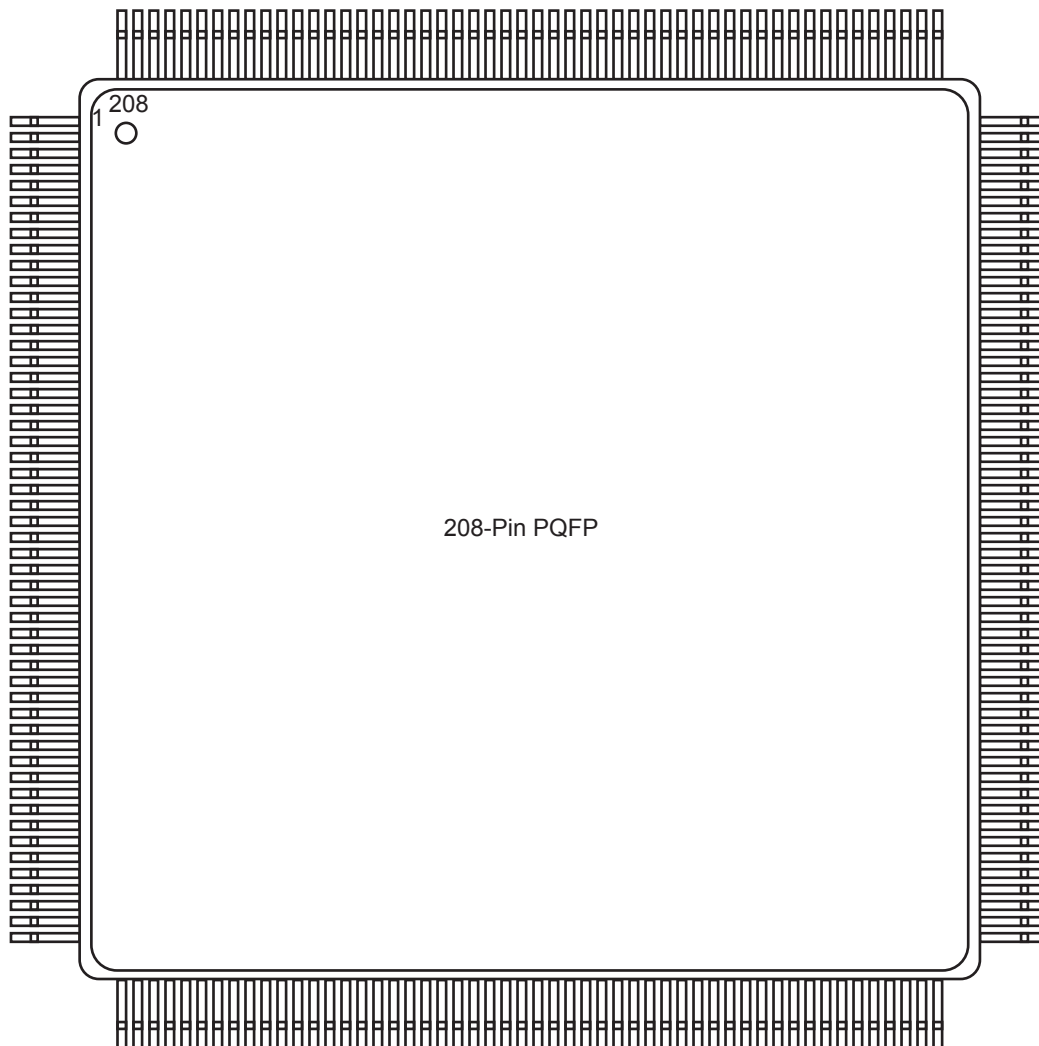
Globals

GL I/Os have access to certain clock conditioning circuitry (and the PLL) and/or have direct access to the global network (spines). Additionally, the global I/Os can be used as regular I/Os, since they have identical capabilities. Unused GL pins are configured as inputs with pull-up resistors.

See more detailed descriptions of global I/O connectivity in the "Clock Conditioning Circuits in Low Power Flash Devices and Mixed Signal FPGAs" chapter of the *ProASIC3E FPGA Fabric User's Guide*. All inputs labeled GC/GF are direct inputs into the quadrant clocks. For example, if GAA0 is used for an input, GAA1 and GAA2 are no longer available for input to the quadrant globals. All inputs labeled GC/GF are direct inputs into the chip-level globals, and the rest are connected to the quadrant globals. The inputs to the global network are multiplexed, and only one input can be used as a global input.

4 – Package Pin Assignments

PQ208

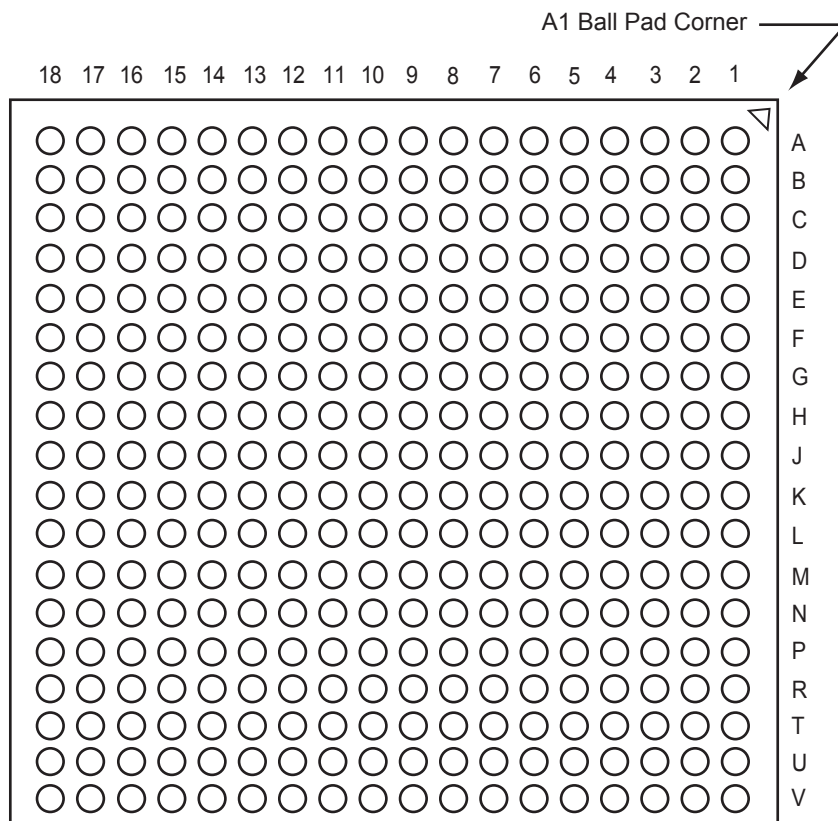


Note: This is the top view of the package.

Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.microsemi.com/products/fpga-soc/solutions>.

FG324



Note: This is the bottom view of the package.

Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.microsemi.com/products/fpga-soc/solutions>.

FG484	
Pin Number	A3PE1500 Function
H19	IO67PDB2V1
H20	VCC
H21	VMV2
H22	IO74PSB2V2
J1	IO212NDB7V2
J2	IO212PDB7V2
J3	VMV7
J4	IO206PDB7V1
J5	IO204PDB7V1
J6	IO210PDB7V2
J7	IO215NDB7V3
J8	VCCIB7
J9	GND
J10	VCC
J11	VCC
J12	VCC
J13	VCC
J14	GND
J15	VCCIB2
J16	IO60NDB2V0
J17	IO65NDB2V1
J18	IO65PDB2V1
J19	IO75PPB2V2
J20	GNDQ
J21	IO77PDB2V2
J22	IO79PDB2V3
K1	IO200NDB7V1
K2	IO200PDB7V1
K3	GNDQ
K4	IO206NDB7V1
K5	IO204NDB7V1
K6	IO210NDB7V2
K7	GFC1/IO192PPB7V0
K8	VCCIB7
K9	VCC
K10	GND

FG484	
Pin Number	A3PE1500 Function
K11	GND
K12	GND
K13	GND
K14	VCC
K15	VCCIB2
K16	GCC1/IO85PPB2V3
K17	IO73NDB2V2
K18	IO73PDB2V2
K19	IO81NPB2V3
K20	IO75NPB2V2
K21	IO77NDB2V2
K22	IO79NDB2V3
L1	NC
L2	IO196PDB7V0
L3	IO196NDB7V0
L4	GFB0/IO191NPB7V0
L5	GFA0/IO190NDB6V2
L6	GFB1/IO191PPB7V0
L7	VCOMPLF
L8	GFC0/IO192NPB7V0
L9	VCC
L10	GND
L11	GND
L12	GND
L13	GND
L14	VCC
L15	GCC0/IO85NPB2V3
L16	GCB1/IO86PPB2V3
L17	GCA0/IO87NPB3V0
L18	VCOMPLC
L19	GCB0/IO86NPB2V3
L20	IO81PPB2V3
L21	IO83NDB2V3
L22	IO83PDB2V3
M1	GNDQ
M2	IO185NPB6V2

FG484	
Pin Number	A3PE1500 Function
M3	IO189NDB6V2
M4	GFA2/IO189PDB6V2
M5	GFA1/IO190PDB6V2
M6	VCCPLF
M7	IO188NDB6V2
M8	GFB2/IO188PDB6V2
M9	VCC
M10	GND
M11	GND
M12	GND
M13	GND
M14	VCC
M15	GCB2/IO89PPB3V0
M16	GCA1/IO87PPB3V0
M17	GCC2/IO90PPB3V0
M18	VCCPLC
M19	GCA2/IO88PDB3V0
M20	IO88NDB3V0
M21	IO93PDB3V0
M22	NC
N1	IO185PPB6V2
N2	IO183NDB6V2
N3	VMV6
N4	GFC2/IO187PPB6V2
N5	IO184PPB6V2
N6	IO186PDB6V2
N7	IO186NDB6V2
N8	VCCIB6
N9	VCC
N10	GND
N11	GND
N12	GND
N13	GND
N14	VCC
N15	VCCIB3
N16	IO89NPB3V0

FG484	
Pin Number	A3PE1500 Function
N17	IO91NPB3V0
N18	IO90NPB3V0
N19	IO91PPB3V0
N20	GNDQ
N21	IO93NDB3V0
N22	IO95PDB3V1
P1	NC
P2	IO183PDB6V2
P3	IO187NPB6V2
P4	IO184NPB6V2
P5	IO176PPB6V1
P6	IO182PDB6V1
P7	IO182NDB6V1
P8	VCCIB6
P9	GND
P10	VCC
P11	VCC
P12	VCC
P13	VCC
P14	GND
P15	VCCIB3
P16	GDB0/IO109NPB3V2
P17	IO97NDB3V1
P18	IO97PDB3V1
P19	IO99PDB3V1
P20	VMV3
P21	IO98PDB3V1
P22	IO95NDB3V1
R1	NC
R2	IO177PDB6V1
R3	VCC
R4	IO176NPB6V1
R5	IO174NDB6V0
R6	IO174PDB6V0
R7	GEC0/IO169NPB6V0
R8	VMV5

FG484	
Pin Number	A3PE1500 Function
R9	VCCIB5
R10	VCCIB5
R11	IO135NDB5V0
R12	IO135PDB5V0
R13	VCCIB4
R14	VCCIB4
R15	VMV3
R16	VCCPLD
R17	GDB1/IO109PPB3V2
R18	GDC1/IO108PDB3V2
R19	IO99NDB3V1
R20	VCC
R21	IO98NDB3V1
R22	IO101PDB3V1
T1	NC
T2	IO177NDB6V1
T3	NC
T4	IO171PDB6V0
T5	IO171NDB6V0
T6	GEC1/IO169PPB6V0
T7	VCOMPLE
T8	GNDQ
T9	GEA2/IO166PPB5V3
T10	IO145NDB5V1
T11	IO141NDB5V0
T12	IO139NDB5V0
T13	IO119NDB4V1
T14	IO119PDB4V1
T15	GNDQ
T16	VCOMPLD
T17	VJTAG
T18	GDC0/IO108NDB3V2
T19	GDA1/IO110PDB3V2
T20	NC
T21	IO103PDB3V2
T22	IO101NDB3V1

FG484	
Pin Number	A3PE1500 Function
U1	IO175PPB6V1
U2	IO173PDB6V0
U3	IO173NDB6V0
U4	GEB1/IO168PDB6V0
U5	GEB0/IO168NDB6V0
U6	VMV6
U7	VCCPLE
U8	IO166NPB5V3
U9	IO157PPB5V2
U10	IO145PDB5V1
U11	IO141PDB5V0
U12	IO139PDB5V0
U13	IO121NDB4V1
U14	IO121PDB4V1
U15	VMV4
U16	TCK
U17	VPUMP
U18	TRST
U19	GDA0/IO110NDB3V2
U20	NC
U21	IO103NDB3V2
U22	IO105PDB3V2
V1	NC
V2	IO175NPB6V1
V3	GND
V4	GEA1/IO167PDB6V0
V5	GEA0/IO167NDB6V0
V6	GNDQ
V7	GEC2/IO164PDB5V3
V8	IO157NPB5V2
V9	IO151NDB5V2
V10	IO151PDB5V2
V11	IO137NDB5V0
V12	IO137PDB5V0
V13	IO123NDB4V1
V14	IO123PDB4V1

FG484		FG484		FG484	
Pin Number	A3PE3000 Function	Pin Number	A3PE3000 Function	Pin Number	A3PE3000 Function
A1	GND	AA15	IO170PDB4V2	B7	IO14PDB0V1
A2	GND	AA16	IO166NDB4V1	B8	IO18NDB0V2
A3	VCCIB0	AA17	IO166PDB4V1	B9	IO24NDB0V2
A4	IO10NDB0V1	AA18	IO160NDB4V0	B10	IO34PDB0V4
A5	IO10PDB0V1	AA19	IO160PDB4V0	B11	IO40PDB0V4
A6	IO16NDB0V1	AA20	IO158NPB4V0	B12	IO46NDB1V0
A7	IO16PDB0V1	AA21	VCCIB3	B13	IO54NDB1V1
A8	IO18PDB0V2	AA22	GND	B14	IO62NDB1V2
A9	IO24PDB0V2	AB1	GND	B15	IO62PDB1V2
A10	IO28NDB0V3	AB2	GND	B16	IO68NDB1V3
A11	IO28PDB0V3	AB3	VCCIB5	B17	IO68PDB1V3
A12	IO46PDB1V0	AB4	IO216NDB5V2	B18	IO72PDB1V3
A13	IO54PDB1V1	AB5	IO216PDB5V2	B19	IO74PDB1V4
A14	IO56NDB1V1	AB6	IO210NDB5V2	B20	IO76NPB1V4
A15	IO56PDB1V1	AB7	IO210PDB5V2	B21	VCCIB2
A16	IO64NDB1V2	AB8	IO208NDB5V1	B22	GND
A17	IO64PDB1V2	AB9	IO208PDB5V1	C1	VCCIB7
A18	IO72NDB1V3	AB10	IO197NDB5V0	C2	IO303PDB7V3
A19	IO74NDB1V4	AB11	IO197PDB5V0	C3	IO305PDB7V3
A20	VCCIB1	AB12	IO174NDB4V2	C4	IO06NPB0V0
A21	GND	AB13	IO174PDB4V2	C5	GND
A22	GND	AB14	IO172NDB4V2	C6	IO12NDB0V1
AA1	GND	AB15	IO172PDB4V2	C7	IO12PDB0V1
AA2	VCCIB6	AB16	IO168NDB4V1	C8	VCC
AA3	IO228PDB5V4	AB17	IO168PDB4V1	C9	VCC
AA4	IO224PDB5V3	AB18	IO162NDB4V1	C10	IO34NDB0V4
AA5	IO218NDB5V3	AB19	IO162PDB4V1	C11	IO40NDB0V4
AA6	IO218PDB5V3	AB20	VCCIB4	C12	IO48NDB1V0
AA7	IO212NDB5V2	AB21	GND	C13	IO48PDB1V0
AA8	IO212PDB5V2	AB22	GND	C14	VCC
AA9	IO198PDB5V0	B1	GND	C15	VCC
AA10	IO198NDB5V0	B2	VCCIB7	C16	IO70NDB1V3
AA11	IO188PPB4V4	B3	IO06PPB0V0	C17	IO70PDB1V3
AA12	IO180NDB4V3	B4	IO08NDB0V0	C18	GND
AA13	IO180PDB4V3	B5	IO08PDB0V0	C19	IO76PPB1V4
AA14	IO170NDB4V2	B6	IO14NDB0V1	C20	IO88NDB2V0

FG484		FG484		FG484	
Pin Number	A3PE3000 Function	Pin Number	A3PE3000 Function	Pin Number	A3PE3000 Function
N17	IO132NPB3V2	R9	VCCIB5	U1	IO240PPB6V0
N18	IO117NPB3V0	R10	VCCIB5	U2	IO238PDB6V0
N19	IO132PPB3V2	R11	IO196NDB5V0	U3	IO238NDB6V0
N20	GNDQ	R12	IO196PDB5V0	U4	GEB1/IO235PDB6V0
N21	IO126NDB3V1	R13	VCCIB4	U5	GEB0/IO235NDB6V0
N22	IO128PDB3V1	R14	VCCIB4	U6	VMV6
P1	IO247PDB6V1	R15	VMV3	U7	VCCPLE
P2	IO253PDB6V2	R16	VCCPLD	U8	IO233NPB5V4
P3	IO270NPB6V4	R17	GDB1/IO152PPB3V4	U9	IO222PPB5V3
P4	IO261NPB6V3	R18	GDC1/IO151PDB3V4	U10	IO206PDB5V1
P5	IO249PPB6V1	R19	IO138NDB3V3	U11	IO202PDB5V1
P6	IO259PDB6V3	R20	VCC	U12	IO194PDB5V0
P7	IO259NDB6V3	R21	IO130NDB3V2	U13	IO176NDB4V2
P8	VCCIB6	R22	IO134PDB3V2	U14	IO176PDB4V2
P9	GND	T1	IO243PPB6V1	U15	VMV4
P10	VCC	T2	IO245NDB6V1	U16	TCK
P11	VCC	T3	IO243NPB6V1	U17	VPUMP
P12	VCC	T4	IO241PDB6V0	U18	TRST
P13	VCC	T5	IO241NDB6V0	U19	GDA0/IO153NDB3V4
P14	GND	T6	GEC1/IO236PPB6V0	U20	IO144NDB3V3
P15	VCCIB3	T7	VCOMPLE	U21	IO140NDB3V3
P16	GDB0/IO152NPB3V4	T8	GNDQ	U22	IO142PDB3V3
P17	IO136NDB3V2	T9	GEA2/IO233PPB5V4	V1	IO239PDB6V0
P18	IO136PDB3V2	T10	IO206NDB5V1	V2	IO240NPB6V0
P19	IO138PDB3V3	T11	IO202NDB5V1	V3	GND
P20	VMV3	T12	IO194NDB5V0	V4	GEA1/IO234PDB6V0
P21	IO130PDB3V2	T13	IO186NDB4V4	V5	GEA0/IO234NDB6V0
P22	IO128NDB3V1	T14	IO186PDB4V4	V6	GNDQ
R1	IO247NDB6V1	T15	GNDQ	V7	GEC2/IO231PDB5V4
R2	IO245PDB6V1	T16	VCOMPLD	V8	IO222NPB5V3
R3	VCC	T17	VJTAG	V9	IO204NDB5V1
R4	IO249NPB6V1	T18	GDC0/IO151NDB3V4	V10	IO204PDB5V1
R5	IO251NDB6V2	T19	GDA1/IO153PDB3V4	V11	IO195NDB5V0
R6	IO251PDB6V2	T20	IO144PDB3V3	V12	IO195PDB5V0
R7	GEC0/IO236NPB6V0	T21	IO140PDB3V3	V13	IO178NDB4V3
R8	VMV5	T22	IO134NDB3V2	V14	IO178PDB4V3

FG896		FG896		FG896	
Pin Number	A3PE3000 Function	Pin Number	A3PE3000 Function	Pin Number	A3PE3000 Function
AC21	IO164PDB4V1	AD27	GDA0/IO153NDB3V4	AF3	VCCIB6
AC22	IO162PPB4V1	AD28	GDC0/IO151NDB3V4	AF4	IO220NPB5V3
AC23	GND	AD29	GDC1/IO151PDB3V4	AF5	VCC
AC24	VCOMPLD	AD30	GND	AF6	IO228NDB5V4
AC25	IO150NDB3V4	AE1	IO242PPB6V1	AF7	VCCIB5
AC26	IO148NDB3V4	AE2	VCC	AF8	IO230PDB5V4
AC27	GDA1/IO153PDB3V4	AE3	IO239PDB6V0	AF9	IO229NDB5V4
AC28	IO145NDB3V3	AE4	IO239NDB6V0	AF10	IO229PDB5V4
AC29	IO143NDB3V3	AE5	VMV6	AF11	IO214PPB5V2
AC30	IO137NDB3V2	AE6	GND	AF12	IO208NDB5V1
AD1	GND	AE7	GNDQ	AF13	IO208PDB5V1
AD2	IO242NPB6V1	AE8	IO230NDB5V4	AF14	IO200PDB5V0
AD3	IO240NDB6V0	AE9	IO224NPB5V3	AF15	IO196NDB5V0
AD4	GEC0/IO236NDB6V0	AE10	IO214NPB5V2	AF16	IO186NDB4V4
AD5	VCCIB6	AE11	IO212NDB5V2	AF17	IO186PDB4V4
AD6	GNDQ	AE12	IO212PDB5V2	AF18	IO180NDB4V3
AD7	VCC	AE13	IO202NPB5V1	AF19	IO180PDB4V3
AD8	VMV5	AE14	IO200NDB5V0	AF20	IO168NDB4V1
AD9	VCCIB5	AE15	IO196PDB5V0	AF21	IO168PDB4V1
AD10	IO224PPB5V3	AE16	IO190NDB4V4	AF22	IO160NDB4V0
AD11	IO218NPB5V3	AE17	IO184PDB4V3	AF23	IO158NPB4V0
AD12	IO216PPB5V2	AE18	IO184NDB4V3	AF24	VCCIB4
AD13	IO210PPB5V2	AE19	IO172PDB4V2	AF25	IO154NPB4V0
AD14	IO202PPB5V1	AE20	IO172NDB4V2	AF26	VCC
AD15	IO194PDB5V0	AE21	IO166NDB4V1	AF27	TDO
AD16	IO190PDB4V4	AE22	IO160PDB4V0	AF28	VCCIB3
AD17	IO182NPB4V3	AE23	GNDQ	AF29	GNDQ
AD18	IO176NDB4V2	AE24	VMV4	AF30	GND
AD19	IO176PDB4V2	AE25	GND	AG1	IO238NPB6V0
AD20	IO170PPB4V2	AE26	GDB0/IO152NDB3V4	AG2	VCC
AD21	IO166PDB4V1	AE27	GDB1/IO152PDB3V4	AG3	IO232NPB5V4
AD22	VCCIB4	AE28	VMV3	AG4	GND
AD23	TCK	AE29	VCC	AG5	IO220PPB5V3
AD24	VCC	AE30	IO149PDB3V4	AG6	IO228PDB5V4
AD25	TRST	AF1	GND	AG7	IO231NDB5V4
AD26	VCCIB3	AF2	IO238PPB6V0	AG8	GEC2/IO231PDB5V4

Revision	Changes	Page
Revision 3 (Apr 2008) Packaging v1.2	The following pins had duplicates and the extra pins were deleted from the "PQ208" A3PE3000 table: 36, 62, 171 Note: There were no pin function changes in this update.	4-2
	The following pins had duplicates and the extra pins were deleted from the "FG324" table: E2, E3, E16, E17, P2, P3, T16, U17 Note: There were no pin function changes in this update.	4-12
	The "FG256" pin table was updated for the A3PE600 device because the old PAT were based on the IFX die, and this is the final UMC die version.	4-9
	The "FG484" was updated for the A3PE600 device because the old PAT were based on the IFX die, and this is the final UMC die version.	4-22
	The following pins had duplicates and the extra pins were deleted from the "FG896" table: AD6, AE5, AE28, AF29, F5, F26, G6, G25 Note: There were no pin function changes in this update.	4-41
Revision 2 (Mar 2008) Product Brief rev. 1	The FG324 package was added to the "ProASIC3E Product Family" table, the "I/Os Per Package1" table, and the "Temperature Grade Offerings" table for A3PE3000.	I, II, IV
Revision 1 (Feb 2008) DC and Switching Characteristics v1.1	In Table 2-3 • Flash Programming Limits – Retention, Storage and Operating Temperature 1, Maximum Operating Junction Temperature was changed from 110°C to 100°C for both commercial and industrial grades.	2
	The "PLL Behavior at Brownout Condition" section is new.	2-4
	In the "PLL Contribution—PPLL" section, the following was deleted: FCLKIN is the input clock frequency.	2-10
	In Table 2-14 • Summary of Maximum and Minimum DC Input Levels, the note was incorrect. It previously said T _J and it was corrected and changed to T _A .	2-17
	In Table 2-98 • ProASIC3E CCC/PLL Specification, the SCLK parameter and note 1 are new.	2-70
	Table 2-103 • JTAG 1532 was populated with the parameter data, which was not in the previous version of the document.	2-83
Revision 1 (cont'd) Packaging v1.1	The "PQ208" pin table for A3PE3000 was updated.	4-2
	The "FG324" pin table for A3PE3000 is new.	4-13
	The "FG484" pin table for A3PE3000 is new.	4-17
	The "FG896" pin table for A3PE3000 is new.	4-41
Revision 0 (Jan 2008)	This document was previously in datasheet v2.1. As a result of moving to the handbook format, Actel has restarted the version numbers. The new version number is 51700098-001-0.	N/A
v2.1 (July 2007)	CoreMP7 information was removed from the "Features and Benefits" section.	1-I
	The M1 device part numbers have been updated in ProASIC3E Product Family, "Packaging Tables", "Temperature Grade Offerings", "Speed Grade and Temperature Grade Matrix", and "Speed Grade and Temperature Grade Matrix".	1-I